ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES	annockburn, Illinois. A	All rights reserved un ntions.	ider both lev	is docume vel parts, th	ent is a declaration the declaration en	n of the substance compasses all low	es within the manufactur wer level materials for w	er listed iten	n. Note: if t ufacturer h	he item is an as as engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut			<ul> <li>Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infe</li> </ul>					Informatio	n		
Supplier Information												
Company name* Company unique ID			Unique ID Authority			ority	Resp			sponse Date*		
emi									2024-05-20			
Contact Name	Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative				Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Enviro Comp			Compliance NA			A			Product-Env-Stewards@onsemi.com			
Requester Item Number N	Ifr Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site	We	ight*	UOM	Unit Type	
L	M317MBDTG	MBDTG ANA 500MA ADJU		j	2024-05-20		MY1	350	).99	mg	Each	
Manufacturing Proccess Information										·	·	
Terminal Plating / Grid Array Material	erial Terminal Base Alloy J		STD-020 MSL R	ating	Peak Process Body Temperature		ture Max Time at Peak	Temperature Numbe		of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	seconds	3				
Comments												
level 1 - maximum time at peak temperature du	ring soldering is 10-3	0 seconds										
For more information regarding material comp	osition please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part, shall apply.											
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Phenolic Resin	proprietary data		10.372	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		108.2577	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg